

主要材料/BOM 清单信息 (Information of Material/BOM list):

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材料			描述	供应商
1	基板	S23061JL1E	93. 81X93. 81X0. 21	客供
2	晶圆	WUM230SD1M	837.8*966.5(μm²)*200um (不包含bump高度) A芯	客供
3	助焊剂	TACFLUX 026S	/	钢泰

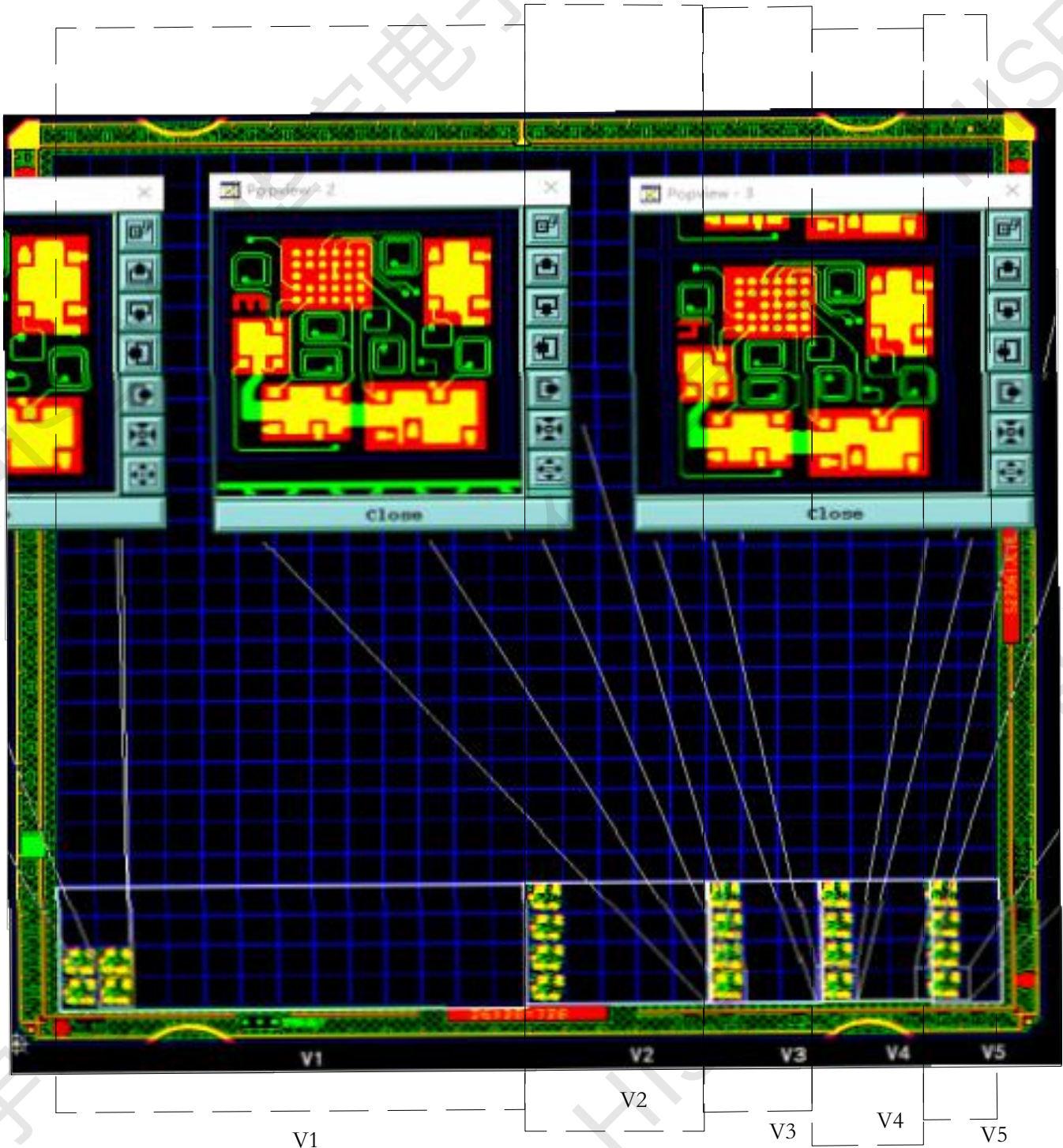
基板切割道宽度

0.09mm



注意：贴装共用一条基板，基板贴V1-V5区域，
根据工单指示封装区域，从左往右，V1第1列
到第13列；V2第14列到第18列；V3第19列到第
21列；V4第22列到第24列；V5第25列到第26
列。

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拟制 Prepared by	制图日期 Create Date	2025/12/26	生效日期 Effective Date	客户确认签字/盖章： Customer Signature
研发审核 R&d check	产品工程审核 Product engineering check		批准 Approved by	

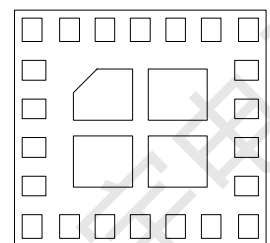
*温馨提示：图纸为产品下线生产的唯一依据，请您认真确认，我司依据您回签后的图纸生产，如图纸错误会产生不可估量损失，谢谢！

*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

PIN1



1.此图纸只做FC倒装贴U2这颗die,U2按照MAP取die;

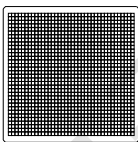


底部示意图

框架传送方向 (装片):
L/F Direction (D/A):

实物图：
Chip photo:

特殊说明 Special Instructions :



按单颗显示方向进料

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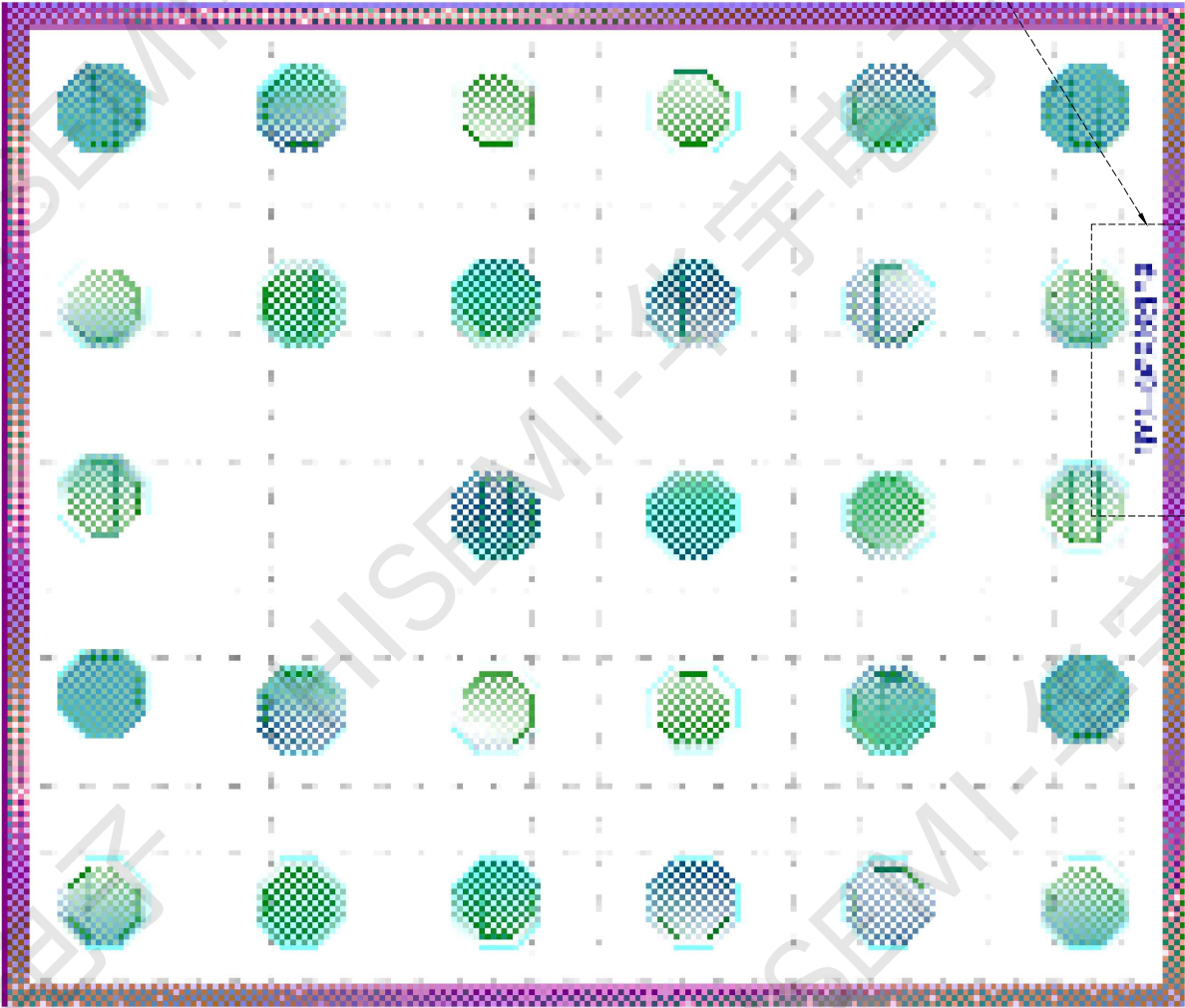
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 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram	客户代码 Customer No.	1200	线图号 Drawing No.	HY-PX-1200-079 A		页码 Page 4 / 5
	产品名称 Product Type	STR21230-61 E2.0 E2.1		封装外型 PKG Type	FCLGA26L(3.2X3.0X0.65-P0.45)	

U2 ball map图 (TOP view)

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按目标区域取DIE:
ID: STR21230-V01

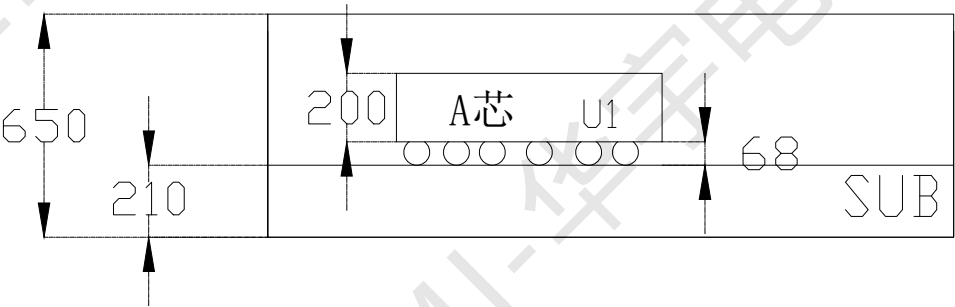


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